# **MMVL109T1**

Preferred Device

# **Silicon Epicap Diodes**

Designed for general frequency control and tuning applications; providing solid-state reliability in replacement of mechanical tuning methods.

### Features

- High Q with Guaranteed Minimum Values at VHF Frequencies
- Controlled and Uniform Tuning Ratio
- Surface Mount Package
- Pb–Free Package is Available

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	V <sub>R</sub>	30	Vdc
Peak Forward Current	١ <sub>F</sub>	200	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board $T_A = 25^{\circ}C$ (Note 1) Derate above 25°C	P <sub>D</sub>	200 1.57	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\thetaJA}$	635	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. FR-5 Minimum Pad



## **ON Semiconductor®**

http://onsemi.com

# 26–32 pF VOLTAGE VARIABLE CAPACITANCE DIODES

1 0 2 CATHODE ANODE



PLASTIC SOD-323 CASE 477 STYLE 1

## MARKING DIAGRAM



4A = Device Code

- M = Date Code\*
- = Pb–Free Package

(Note: Microdot may be in either location) \*Date Code orientation may vary depending upon manufacturing location.

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMVL109T1	SOD-323	3000 / Tape & Reel
MMVL109T1G	SOD-323 (Pb-Free)	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

## **MMVL109T1**

### **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted.)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage (I <sub>R</sub> = 10 μAdc)	V <sub>(BR)R</sub>	30	-	-	Vdc
Reverse Voltage Leakage Current (V <sub>R</sub> = 25 Vdc)	I <sub>R</sub>	-	-	0.1	μAdc
Diode Capacitance Temperature Coefficient $(V_R = 3.0 \text{ Vdc}, f = 1.0 \text{ MHz})$	TC <sub>C</sub>	-	300	-	ppm/°C

	V <sub>R</sub> = 3.0 Vdc, f = 1.0 MHz pF		Q, Figure of Merit V <sub>R</sub> = 3.0 Vdc f = 50 MHz	C <sub>R</sub> , Capacitance Ratio C <sub>3</sub> /C <sub>25</sub> f = 1.0 MHz (Note 2)		
Device			Max	Min	Min	Max
MMVL109T1	26	29	32	200	5.0	6.5

2.  $C_R$  is the ratio of  $C_t$  measured at 3 Vdc divided by  $C_t$  measured at 25 Vdc.

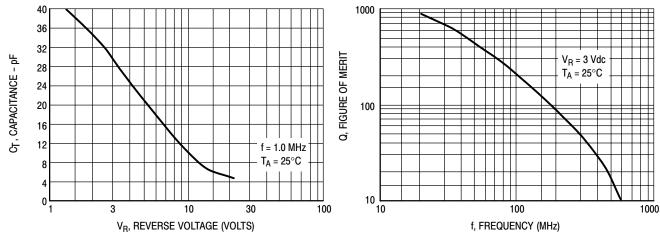
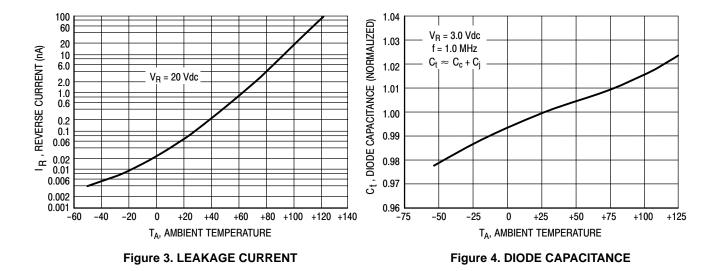


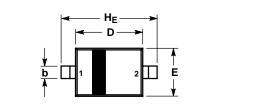


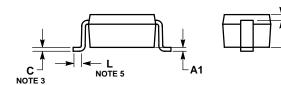
Figure 2. FIGURE OF MERIT



#### PACKAGE DIMENSIONS

SOD-323 CASE 477-02 ISSUE G





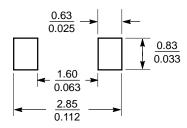
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: MILLIMETERS.
- CONTROLLING DIMENSION: MILLIMETERS.
  LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
- WITH SOLDER PLATING. 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- 5. DIMENSION L IS MEASURED FROM END OF RADIUS.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.80	0.90	1.00	0.031	0.035	0.040	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
A3	0.15 REF			0.006 REF			
b	0.25	0.32	0.4	0.010	0.012	0.016	
С	0.089	0.12	0.177	0.003	0.005	0.007	
D	1.60	1.70	1.80	0.062	0.066	0.070	
E	1.15	1.25	1.35	0.045	0.049	0.053	
L	0.08			0.003			
HE	2.30	2.50	2.70	0.090	0.098	0.105	

STYLE 1: PIN 1. CATHODE 2. ANODE

#### SOLDERING FOOTPRINT\*



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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